

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	65175	(bond\$4 adj (agent or material or substance) or solder\$4 or adhesive or epoxy or glue) and ("tg" or "t.sub.g" or glass adj transition)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/31 13:25
L2	241	1 and ("tg" or "t.sub.g" or glass adj transition) near (pcb or pwb or board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/31 13:27
L3	193	2 and (press\$4 or force or load)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/31 13:27
L4	35	3 and (pcb or pwb or board or substrate) near (warp\$6 or deform\$7 or melt\$4 or soften\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/31 13:35
L5	0	3 and (pcb or pwb or board or substrate) near (plastic\$6 near deform\$7)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/31 13:28
L6	10	4 and solder\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/31 13:36